HOSTAFORM® S 9243 XAP®2 LS

HOSTAFORM®

POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than unmodified acetal copolymer. Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Preliminary Datasheet for natural and colored grades

Product information

Resin Identification	POM-HI		ISO 1043
Part Marking Code	>POM-HI<		ISO 11469

Rheological properties

Melt volume-flow rate	4	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	
Molding shrinkage, parallel	1.9	%	ISO 294-4, 2577
Molding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	283000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	6400	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	40	%	ISO 527-1/-2
Flexural modulus	268000	psi	ISO 178
Tensile creep modulus, 1h	247000	psi	ISO 899-1
Tensile creep modulus, 1000h	138000	psi	ISO 899-1
Charpy impact strength, 23°C	N	$ftlb/in^2$	ISO 179/1eU
Charpy impact strength, -30°C	95.1[P]	$ftlb/in^2$	ISO 179/1eU
Charpy notched impact strength, 23°C	7.14	$ftlb/in^2$	ISO 179/1eA
Charpy notched impact strength, -30°C	4.28	$ftlb/in^2$	ISO 179/1eA

[P]: Partial Break

Thermal properties

Melting temperature, 10°C/min	331	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	167	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.67	E-4/°F	ISO 11359-1/-2

Flammability

FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	1.93	in/min	ISO 3795 (FMVSS 302)

Electrical properties

Relative permittivity, 100Hz	3.8		IEC 62631-2-1
Relative permittivity, 1MHz	3.8		IEC 62631-2-1
Dissipation factor, 100Hz	30	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	60	E-4	IEC 62631-2-1
Volume resistivity	1E11	Ohm.m	IEC 62631-3-1
Surface resistivity	1E13	Ohm	IEC 62631-3-2
Comparative tracking index	600		IEC 60112

HOSTAFORM® S 9243 XAP®2 LS

HOSTAFORM®

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	1	%	Sim. to ISO 62
Density	0.048	lb/in³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	383	°F
Min. melt temperature	374	°F
Max. melt temperature	392	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	158	°F
Min. mold temperature	140	°F
Max. mold temperature	176	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	2h²-3	s
Back pressure	290	psi

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF
Stellantis - Chrysler	MS.50095 / CPN-4291	Natural

Characteristics

Processing	Injection Molding
Additives	Release agent
Special characteristics	High impact or impact modified, Light stabilized or stable to light, U.V. stabilized or stable to weather, Low emissions, Improved weld line

Additional information

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

Storage

The product can then be stored in standard conditions until processed.

HOSTAFORM® S 9243 XAP®2 LS

HOSTAFORM®

Revised: 2026-08-12 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colorants or other additives may cause significant variations in data values. Properties of molded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.
Copyright © 2026 Celanese or its affiliates. All rights reserved.
Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates.